

ADSL Line LPAnformer

Link-PP Int'l Technology

- ※ For Globespan G7000 ADSL Chipset
- ※ Designed for CenLPAI Office (CO) and Customer Premise (CPE) applications
- ※ Excellent THD performance in a small footprint
- ※ Designed to meet UL 1950 and EN60950 supplementary insulation requirements for working voltages up to 250 Vrms
- ※ For RoHS part add suffix NL
- ※ RoHS NL peak solder rating 235°C



Electrical Specifications @ 25°C --- Operating Temperature -40°C to +85°C

Part Number	Mounting	Application	Turns Ratio (±2%)	OCL @10kHz,0.1V		Leakage Inductance @100kHz ,0.1V(MAX)	Longitudinal Balance
				(1-5)with(2-4)shorted	(10-6)with(7-9)shorted		
LPA2088	SMT	CPE	1:1	430µH ±10%	430µH ±10%	10µH (1-5)with2-4,7-9,10-6shorted	≤-40dB (25KHz -1,1MHz)
LPA2201	SMT	CO	1:1.42	237µH ±10%	474µH ±10%	15µH (10-6)with7-9,1-4,2-5shorted	≤-60dB (20KHz -1MHz)

Additional Specifications

Part Number	THD Typical (Linearity)	DC Resistance (Ω - MAX)		Isolation Voltage (Vrms)	Insertion Loss (MAX)
		Line Side	Chip Side		
LPA2088	≤80 dB @100kHz	≤.45 (1-4) = (2-5)	≤.35 (10-7) = (9-6)	1875	≤0.50dB @772kHz
LPA2201	≤70dB@200 kHz	≤2.0 (1-5) with 2-4 shorted	≤2.0 (10-6) with 7-9 shorted	2000	≤1.00dB@150 kHz -1.5MHz

Mechanicals

Schematic

LPA2XXX

